

ABSTRACT OF DISCLOSURE

A thermal interface material including a compound which has high thermal conductivity, is dry-to-the-touch, but naturally tacky, and may be formed into various shapes, such as sheets and blocks, to serve as a heat transfer material for electronic components. The compound includes a pre-blend of a polyol ester and an antioxidant, a boron nitride filler, a high viscosity oil, and either a solvent, a surfactant, and a polystyrene-based polymer, or aluminum silicate. A method for using the compound includes the steps of providing a heat generating electronic component with a first surface; providing a heat dissipating component with a second surface with which the first surface is to interface; and disposing the compound between the respective surfaces to effectuate efficient heat transfer therebetween. Further, a removable liner can be applied to an exposed surface of the compound.